

REMARKS

Applicant has amended the specification to correct a typographical error in the serial number of a patent document. The patent document, which should have been correctly identified as Japanese Patent No. 63-239820-A2, is found as reference BN in the List of References cited accompanying an Information Disclosure Statement that is filed herewith.

Accordingly, Applicants believe that no new matter is introduced by way of this amendment and entry thereof is respectfully requested.

No fee is believed to be due with this amendment. However, should the Commissioner determine otherwise, he is hereby authorized to charge any additional fees or credit any overpayment to Pennie & Edmonds LLP Deposit Account No. 16-1150. A copy of this sheet is enclosed for accounting purposes.

Respectfully submitted,

Date: May 21, 2002

Richard G.A. Bone

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Limited Recognition Under 37 C.F.R. § 10.9(b)
(Copy of Certificate Enclosed)

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Enclosures

APPENDIX
CHANGES TO SPECIFICATION UPON ENTRY
OF THE PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.115
MAILED MAY 21, 2002

U.S. PATENT APPLICATION SERIAL No. 10/060,109
(ATTORNEY DOCKET NO. 8317-0129-999)

The following mark-up scheme is adopted:

Deleted material is in [brackets].

Inserted material is underlined in bold.

The paragraph beginning at page 5, line 16 and ending at page 5, line 27, is revised as follows:

An example of a physical means of removing particles is buoyancy. Buoyancy is illustrated in Japanese Patent No. [63-239982-A2] **63-239820-A2** and U.S. Pat. No. 4,817,652, where it was shown that gas bubbles could lift dust particles away from the surface of a semiconductor substrate. Gas bubble formation in liquid solution was induced around dust particles, and the buoyancy of the gas bubble released and lifted the particle from a substrate to the surface of the solution. Surface tension forces were described as part of the particle removal mechanism in that the film encasing the bubble would rapidly converge underneath the particle and detach the particle from the surface of the substrate. Thus, a buoyant force is used to overcome an adhesive force. If the surface tension between the liquid and the substrate is higher than that between the liquid and the particle, the liquid will prefer to remain attached to the substrate. Consequently, the liquid will prefer to pass between the particle and the substrate rather than just pass over the particle.